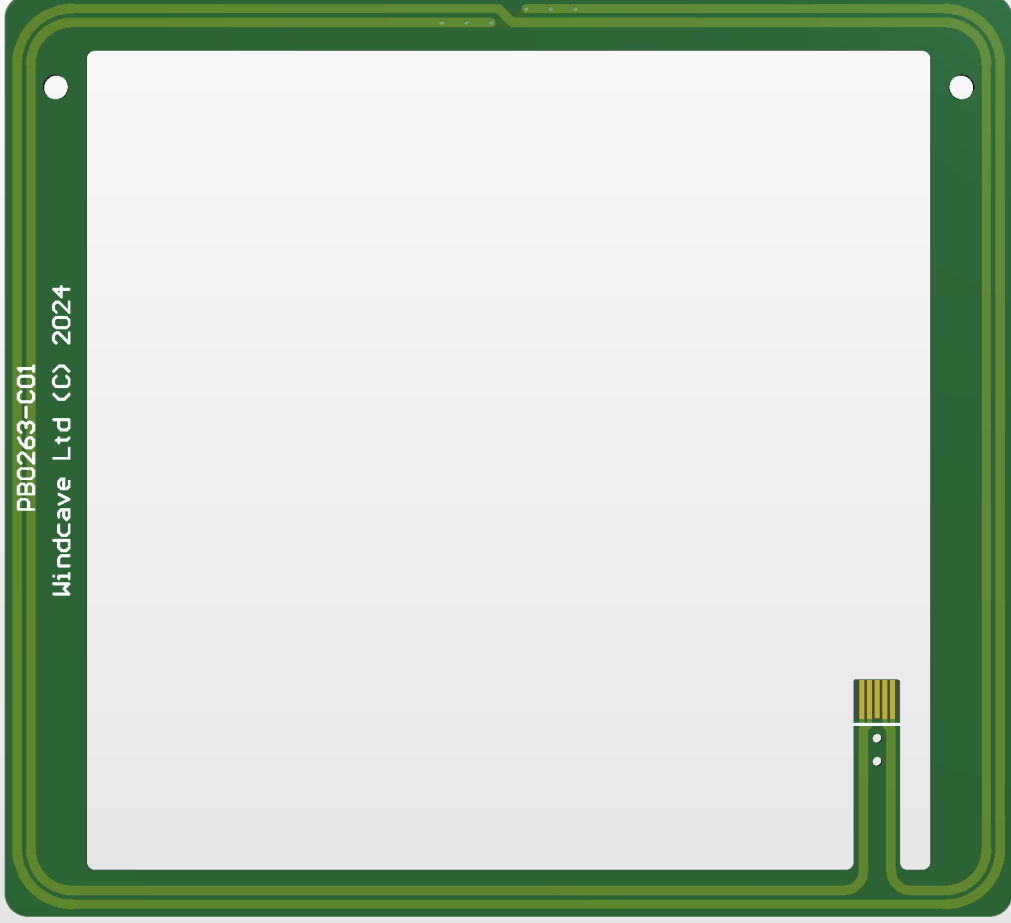
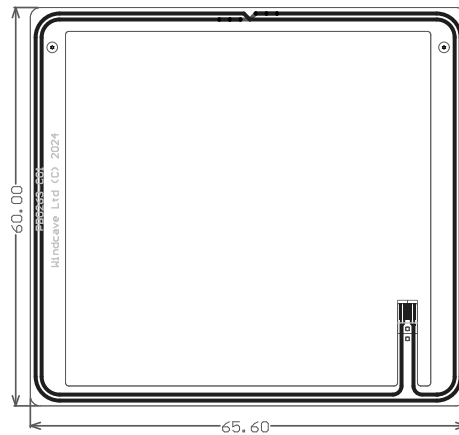






MINIMUM ARTWORK FEATURE SIZE

Track to track:	0.2	mm	0.014	inches
Track to pad:	0.2	mm	0.008	inches
Track width:	0.3	mm	0.014	inches
Drill Hole Size:	0.3	mm	0.012	inches

BOARD TYPE

- ☐ Single Layer, Flex
☒ Double layer, Flex
☐ Multi Layer,
☐ HDI Multi Layer
☐ Embedded PCB Resistor

VIA CONSTRUCTION

- ☐ Blind Vias
☐ Buried Vias
☐ HDI Micro Vias
☐ Stacked HDI Micro Vias

GENERAL NOTES:

1. Finished Board Thickness and Layer Stackup shown in View 'A'
2. All gerber files are in RS274X Metric 4:4 format with embedded apertures.
3. Board shall be fabricated as per IPC-6012B guidelines (unless otherwise stated).
4. ~~Vias are to be epoxy filled and Tented (unless otherwise stated).~~
5. All hole sizes described in this Document are Finished Hole Sizes (FHS).
6. No silkscreen allowed on exposed lands or in holes.
7. Finished boards shall not have nicks, scratches, voids, poor plating or mis-drilled holes
8. The PCB is to be 100% Electrically Tested.
9. No copper to be added or removed from the design, except that which is stated above.
- 10.
- 11.
- 12.
- 13.

MATERIALS

PCB / Panel Size: 60x65.6mm
PCBs Per Panel:
Laminate : Polyimide Dielectric Er = 3.5

Thickness: 0.3mm +/- 10% After Plating
Flammability : UL94-V0 at FPC Tail

PROFILE METHOD

- ☐ Routing, 2mm Rout Path
☐ V-Score 30 Deg

ACCEPTABILITY

- ☐ IPC-3-300
☒ IPC-A-600 Class 2
☐ IPC-A-600 Class 3
☒ UL Approval

SURFACE MOUNT

- ☐ Single Sided
☐ Double Sided

COVER LAYER:

- POLYIMIDE FILM 25um
☒ Top Coverlay
☒ Bottom Coverlay

SCREEN PRINT OVERLAYS:

- ☒ Top Overlay (White)
☐ Bottom Overlay
- TRACK FINISH:**
☐ Hot air leveled
☒ Immersion Gold over Nickel (1u")
☐ OSP (Organic Solder Preservatives)
☐ Silver Imersion (6-20u")
☐ Hard Gold

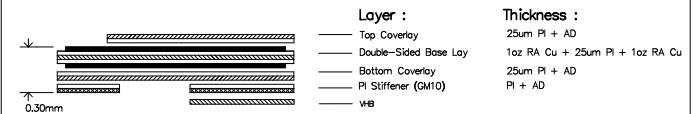
COPPER TYPE:

- ☒ Rolled-annealed (RA)
☐ Half Hard Electro-deposited (ED)

PRODUCTION FILE LIST

DESCRIPTION	FILE
☐	
☒ TOP OVERLAY	GTO
☒ TOP COVERLAY OPENING	GTS
☒ TOP FLEX COPPER LAYER	GTL
☒ BOTTOM FLEX COPPER LAYER	GBL
☒ BOTTOM COVERLAY OPENING	GBS
☐ BOTTOM FR4 STIFFENER	GM9
☒ BOTTOM PI STIFFENER	GM10
☒ BOTTOM VHB	GM24
☐	
☐	
☐	
☐	
☐	
☐	
☒ BOARD OUTLINE	GM1
☐ ROUTE OUTLINE	GM2
☐ V-SCORE OUTLINE	GM3
☐ PASTE SHM OUTLINE	GM14
☐ TOP PASTE MASK	GTP
☐ BOTTOM PASTE MASK	GBP
☒ APERTURE FILE	APR
☒ DRILL DRAWING	GDx
☒ DRILL GUIDE	GGx
☒ NC DRILL - TOOL FILE	DRL
☒ NC DRILL - TEXT FILE	TXx
☒ NC DRILL - BINARY FILE	DRx

VIEW 'A' : LAMINATION STACK-UP STRUCTURE



NOTES:

1. Finished PCB thickness tolerance +/- 10%
2. Finished PCB board outline tolerance +/- 0.1mm

CONTROLLED IMPEDENCE

None

DRILL TABLE

Symbol	Count	Hole Size	Plated	Hole Type
D	2	0.600mm (23.62mil)	NPTH	Round
O	2	1.600mm (62.99mil)	NPTH	Round
O	6	0.300mm (11.81mil)	NPTH	Round
10 Total				

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